

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ATSUSHI MAEDA	02/03/2020
RECEIVING PARTY DATA	
Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.
Street Address:	2520, TAKABA, HITACHINAKA-SHI
City:	IBARAKI
State/Country:	JAPAN
Postal Code:	312-8503
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16630890
CORRESPONDENCE DATA	
Fax Number:	(703)684-1157
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(703) 648-1120
Email:	bvillatoro@mmpiaw.com, docket@mmpiaw.com
Correspondent Name:	MATTINGLY & MALUR PC
Address Line 1:	1800 DIAGONAL ROAD
Address Line 2:	SUITE 210
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	SHI-12451
NAME OF SUBMITTER:	SHRINATH MALUR
SIGNATURE:	/Shrinath Malur/
DATE SIGNED:	03/24/2020
Total Attachments: 1	
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OSP-88010 71

Atty Docket No.:

ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd. (hereinafter referred to as ASSIGNEE), a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki 312-8503 Japan, receipt of which is hereby acknowledged, I do hereby sell and assign to said ASSIGNEE, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to application serial no. 16/630,890, filed January 14, 2020, and entitled: SHOCK ABSORBER AND METHOD OF MANUFACTURING THE SAME

invented by me (if only one inventor is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all non-provisional applications, divisions, continuations and extensions thereof, said interest being the entire ownership of said Letters Patent when granted, to be held and enjoyed by said ASSIGNEE, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, interference proceeding, or post-grant proceeding, or otherwise to secure the title thereto in said assignee;

Whereby, I hereby grant the law firm of MATTINGLY & MALUR, P.C., the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document, including inserting the application serial number and filing date when known.

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said ASSIGNEE.

Signed on the date(s) indicated aside signature(s):

INVENTOR(S)
1) Atsushi Maeda
Atsushi MAEDA

Date Signed
2020/02/03